



AO7400

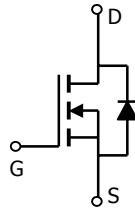
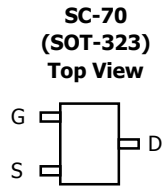
N-Channel Enhancement Mode Field Effect Transistor

General Description

The AO7400 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V, in the small SOT323 footprint.

Features

- V_{DS} (V) = 30V
- I_D = 1.7 A
- $R_{DS(ON)} < 85m\Omega$ ($V_{GS} = 10V$)
- $R_{DS(ON)} < 100m\Omega$ ($V_{GS} = 4.5V$)
- $R_{DS(ON)} < 140m\Omega$ ($V_{GS} = 2.5V$)



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^A	$T_A=25^\circ\text{C}$	1.7	A
	$T_A=70^\circ\text{C}$	1.3	
Pulsed Drain Current ^B	I_{DM}	15	
Power Dissipation ^A	$T_A=25^\circ\text{C}$	0.35	W
	$T_A=70^\circ\text{C}$	0.22	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$		360	$^\circ\text{C/W}$
Maximum Junction-to-Ambient ^A		Steady-State	300	425
Maximum Junction-to-Lead ^C	$R_{\theta JL}$			$^\circ\text{C/W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}$, $V_{GS}=0\text{V}$	30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=24\text{V}$, $V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 12\text{V}$			100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	0.6	1	1.4	V
$I_{D(ON)}$	On state drain current	$V_{GS}=4.5\text{V}$, $V_{DS}=5\text{V}$	10			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$, $I_D=1.5\text{A}$ $T_J=125^\circ\text{C}$		70	85	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=1.5\text{A}$		81	100	$\text{m}\Omega$
		$V_{GS}=2.5\text{V}$, $I_D=1\text{A}$		114	140	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}$, $I_D=1.5\text{A}$		6		S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}$, $V_{GS}=0\text{V}$		0.79	1	V
I_S	Maximum Body-Diode Continuous Current				0.5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}$, $V_{DS}=15\text{V}$, $f=1\text{MHz}$		390		pF
C_{oss}	Output Capacitance			54.5		pF
C_{rSS}	Reverse Transfer Capacitance			41		pF
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $f=1\text{MHz}$		3		Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	$V_{GS}=4.5\text{V}$, $V_{DS}=15\text{V}$, $I_D=1.7\text{A}$		0.62		nC
Q_{gs}	Gate Source Charge			1.58		nC
Q_{gd}	Gate Drain Charge			4.82		nC
$t_{D(on)}$	Turn-On DelayTime	$V_{GS}=10\text{V}$, $V_{DS}=15\text{V}$, $R_L=10.0\Omega$, $R_{GEN}=3\Omega$		2.5		ns
t_r	Turn-On Rise Time			2.3		ns
$t_{D(off)}$	Turn-Off DelayTime			22		ns
t_f	Turn-Off Fall Time			3		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=1.7\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		10		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=1.7\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		3.6		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any a given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D: The static characteristics in Figures 1 to 6, 12, 14 are obtained using 80 μs pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.